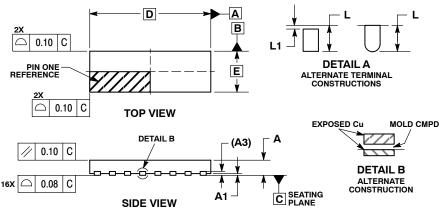
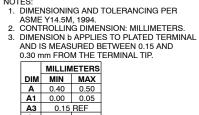


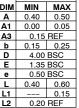
XDFN16 4.0x1.35, **0.5P**CASE 711AZ ISSUE O

DATE 09 SEP 2014





NOTES:



GENERIC MARKING DIAGRAM*

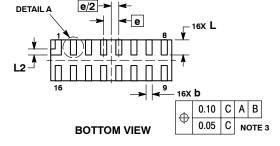


XXX = Specific Device Code

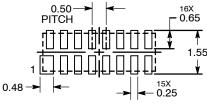
M = Month Code

■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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DESCRIPTION:	XDFN16 4.0X1.35, 0.5P		PAGE 1 OF 1

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^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.